

NTLJS3A18PZ

Power MOSFET

–20 V, –8.2 A, Single P–Channel,
2.0x2.0x0.8 mm WDFN Package

Features

- WDFN Package with Exposed Drain Pads for Excellent Thermal Conduction
- Low Profile WDFN (2.0x2.0x0.8 mm) for Board Space Saving
- Ultra Low $R_{DS(on)}$
- ESD Diode–Protected Gate
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Optimized for Power Management Applications for Portable Products, such as Smart Phones, Media Tablets, PMP, DSC, GPS, and Others
- Battery Switch
- High Side Load Switch

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain–to–Source Voltage			V_{DS}	–20	V
Gate–to–Source Voltage			V_{GS}	± 8.0	V
Continuous Drain Current (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	I_D	–8.2	A
		$T_A = 85^\circ\text{C}$		–5.9	
	$t \leq 5 \text{ s}$	$T_A = 25^\circ\text{C}$		–11.2	
Power Dissipation (Note 1)	Steady State	$T_A = 25^\circ\text{C}$	P_D	1.8	W
		$t \leq 5 \text{ s}$		3.4	
Continuous Drain Current (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	I_D	–5.0	A
		$T_A = 85^\circ\text{C}$		–3.6	
Power Dissipation (Note 2)	Steady State	$T_A = 25^\circ\text{C}$	P_D	0.7	W
Pulsed Drain Current	$t_p = 10 \mu\text{s}$		I_{DM}	–40	A
Operating Junction and Storage Temperature			T_J, T_{STG}	–55 to 150	$^\circ\text{C}$
ESD (HBM, JESD22–A114)			V_{ESD}	2000	V
Source Current (Body Diode) (Note 2)			I_S	–1.1	A
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

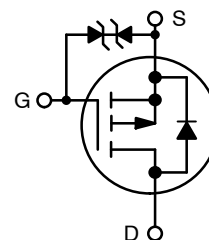
1. Surface Mounted on FR4 Board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).
2. Surface Mounted on FR4 Board using the minimum recommended pad size, (30 mm², 2 oz Cu).



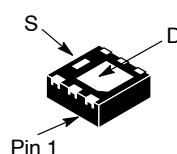
ON Semiconductor®

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$V_{(BR)DS}$	$R_{DS(on)}$ MAX	I_D MAX
–20 V	18 m Ω @ –4.5 V	–8.2 A
	25 m Ω @ –2.5 V	
	50 m Ω @ –1.8 V	
	90 m Ω @ –1.5 V	



P-CHANNEL MOSFET

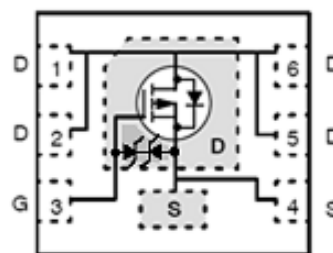


MARKING DIAGRAM



AC = Specific Device Code
M = Date Code
■ = Pb–Free Package
(Note: Microdot may be in either location)

PIN CONNECTIONS



(Top View)

ORDERING INFORMATION

Device	Package	Shipping†
NTLJS3A18PZTWG	WDFN6	10000/Tape & Reel
NTLJS3A18PZTXG	(Pb–Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NTLJS3A18PZ

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 1)	$R_{\theta JA}$	69	°C/W
Junction-to-Ambient – $t \leq 5$ s (Note 1)	$R_{\theta JA}$	37	
Junction-to-Ambient – Steady State Min Pad (Note 2)	$R_{\theta JA}$	186	

MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-20			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = -250\text{ }\mu\text{A}$, Ref to 25°C		11.5		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}, T_J = 25^\circ\text{C}$			-1.0	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5.0\text{ V}$			± 5.0	μA

ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\text{ }\mu\text{A}$	-0.4		-1.0	V
Gate Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$			3.9		mV/°C
Drain-to-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -7.0\text{ A}$		14.6	18	m Ω
		$V_{GS} = -2.5\text{ V}, I_D = -5.0\text{ A}$		20	25	
		$V_{GS} = -1.8\text{ V}, I_D = -3.0\text{ A}$		25	50	
		$V_{GS} = -1.5\text{ V}, I_D = -1.0\text{ A}$		40	90	
Forward Transconductance	g_{FS}	$V_{DS} = -15\text{ V}, I_D = -3.0\text{ A}$		40		S

CHARGES, CAPACITANCES AND GATE RESISTANCE

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = -15\text{ V}$		2240		pF
Output Capacitance	C_{OSS}			240		
Reverse Transfer Capacitance	C_{RSS}			210		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5\text{ V}, V_{DS} = -15\text{ V}, I_D = -4.0\text{ A}$		28		nC
Threshold Gate Charge	$Q_{G(TH)}$			1.0		
Gate-to-Source Charge	Q_{GS}			2.9		
Gate-to-Drain Charge	Q_{GD}			8.8		

SWITCHING CHARACTERISTICS (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -4.5\text{ V}, V_{DD} = -15\text{ V}, I_D = -4.0\text{ A}, R_G = 1.0\text{ }\Omega$		8.6		ns
Rise Time	t_r			15		
Turn-Off Delay Time	$t_{d(OFF)}$			150		
Fall Time	t_f			88		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Recovery Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = -1.0\text{ A}$	$T_J = 25^\circ\text{C}$	-0.63	-1.0	V
			$T_J = 125^\circ\text{C}$	-0.50		
Reverse Recovery Time	t_{RR}	$V_{GS} = 0\text{ V}, dI_{SD}/dt = 100\text{ A}/\mu\text{s}, I_S = -1.0\text{ A}$		26.1		ns
Charge Time	t_a			10.2		
Discharge Time	t_b			15.9		
Reverse Recovery Time	Q_{RR}			12		nC

3. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

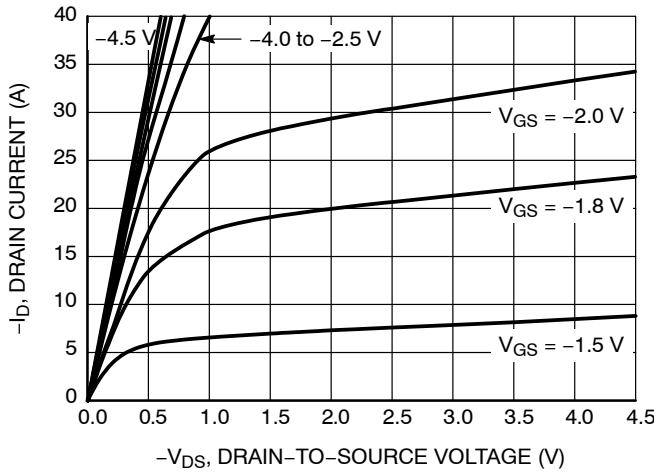


Figure 1. On-Region Characteristics

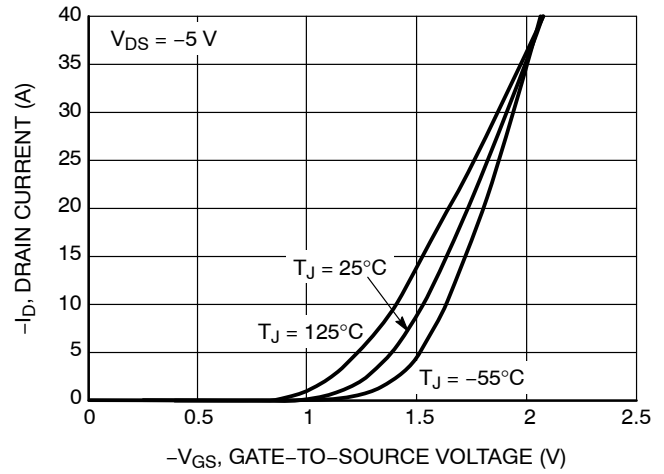


Figure 2. Transfer Characteristics

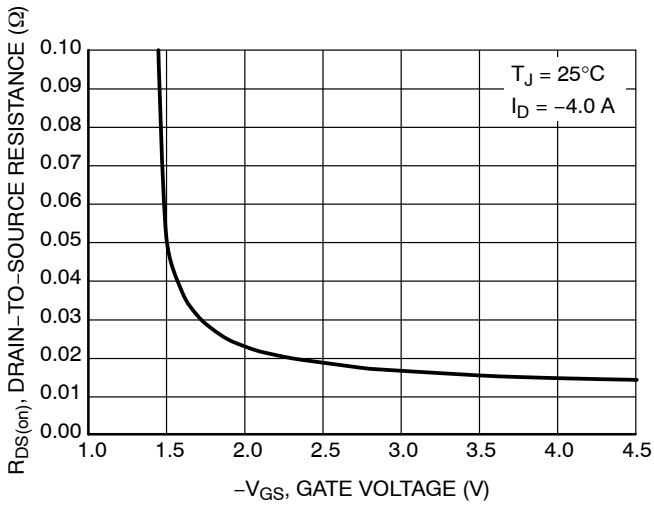


Figure 3. On-Resistance vs. Gate-to-Source Voltage

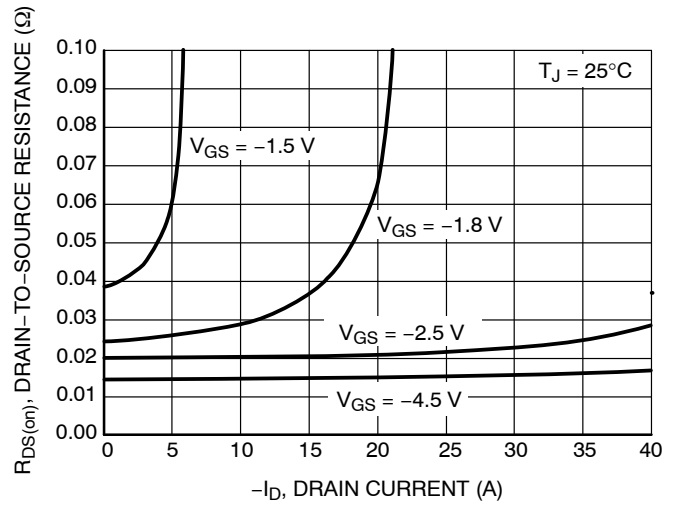


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

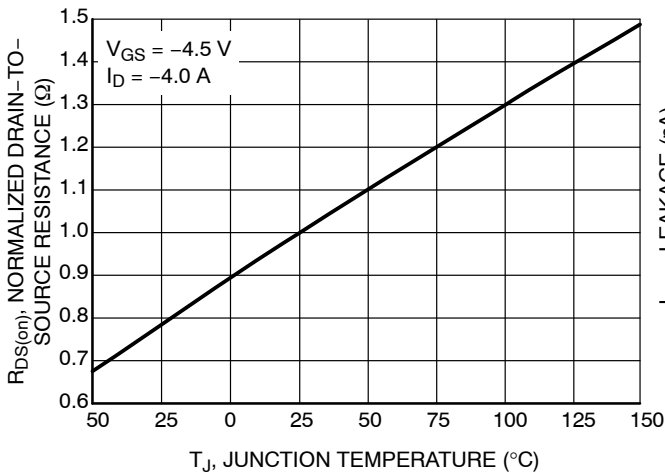


Figure 5. On-Resistance Variation with Temperature

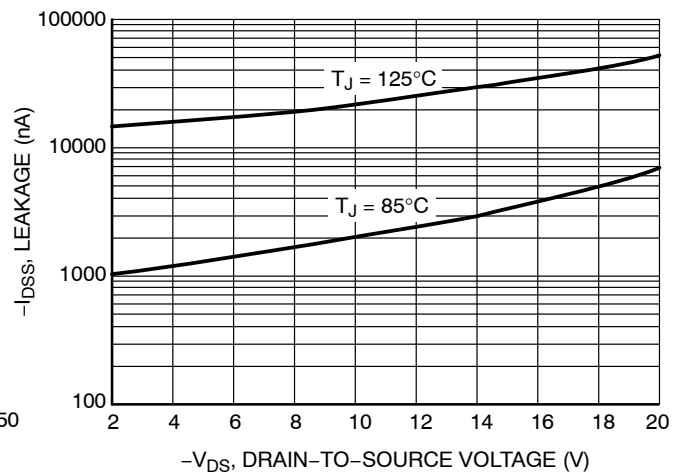


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

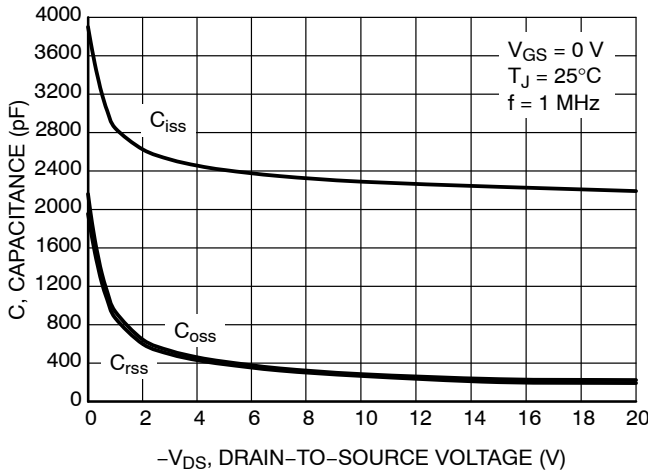


Figure 7. Capacitance Variation

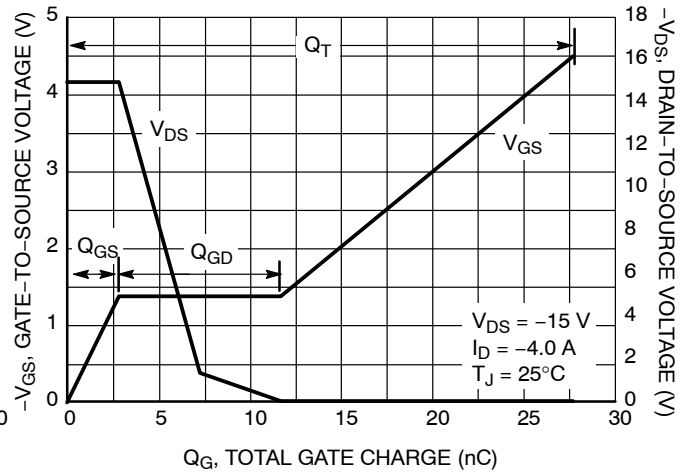


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

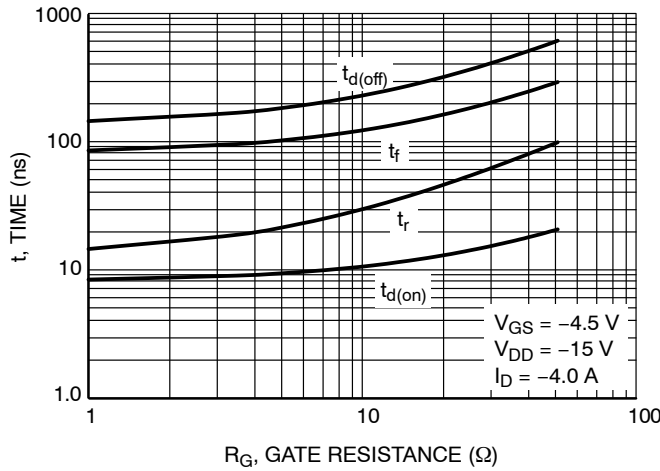


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

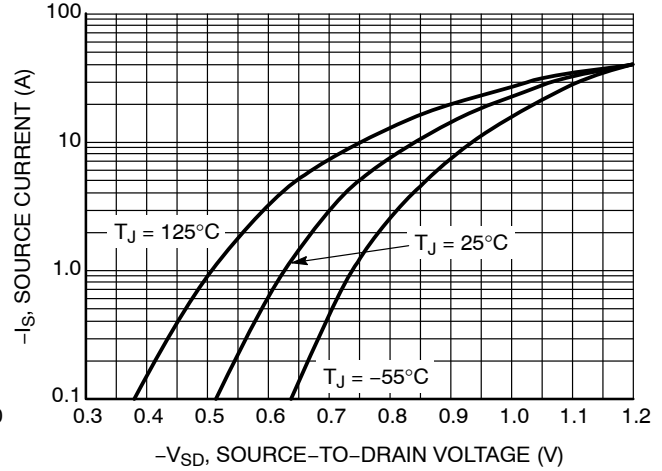


Figure 10. Diode Forward Voltage vs. Current

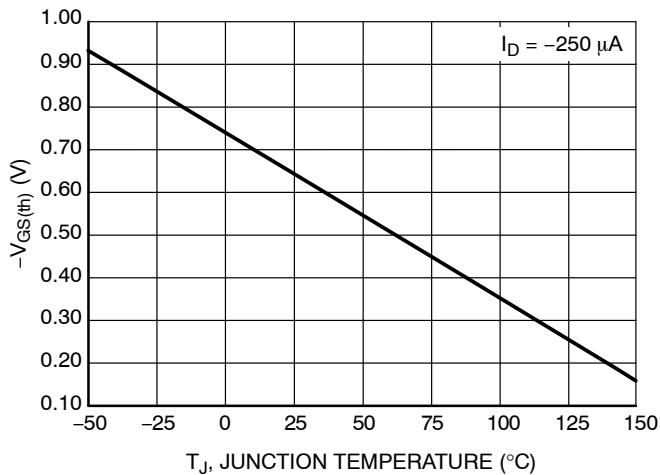


Figure 11. Threshold Voltage

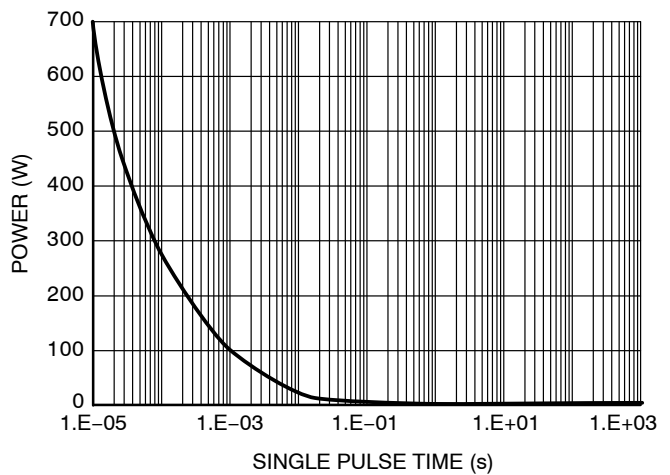


Figure 12. Single Pulse Maximum Power Dissipation

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TYPICAL CHARACTERISTICS

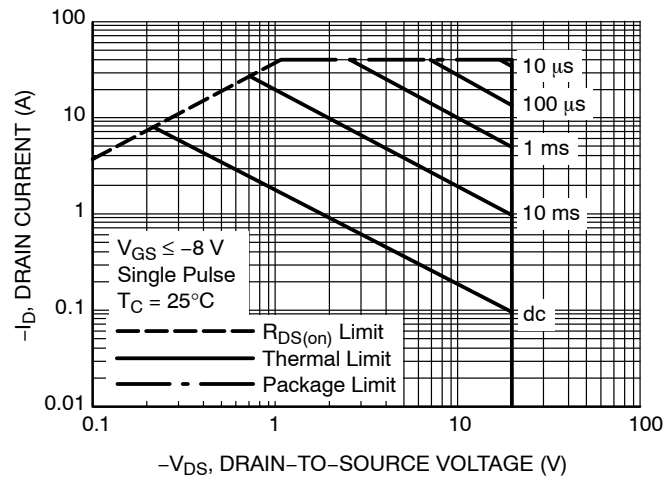


Figure 13. Maximum Rated Forward Biased Safe Operating Area

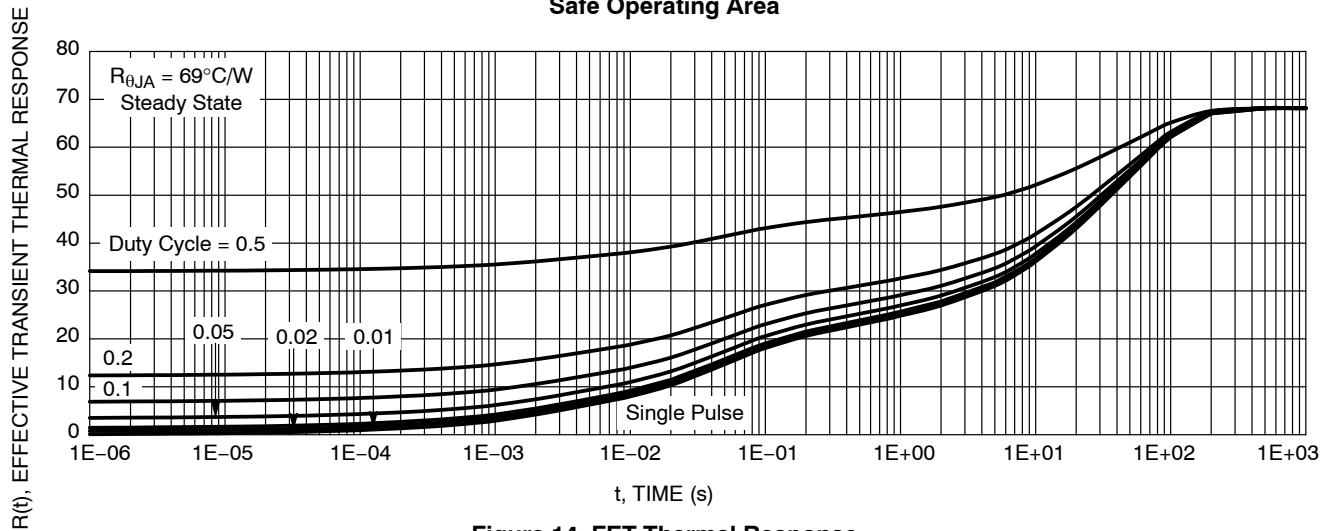
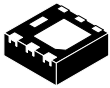


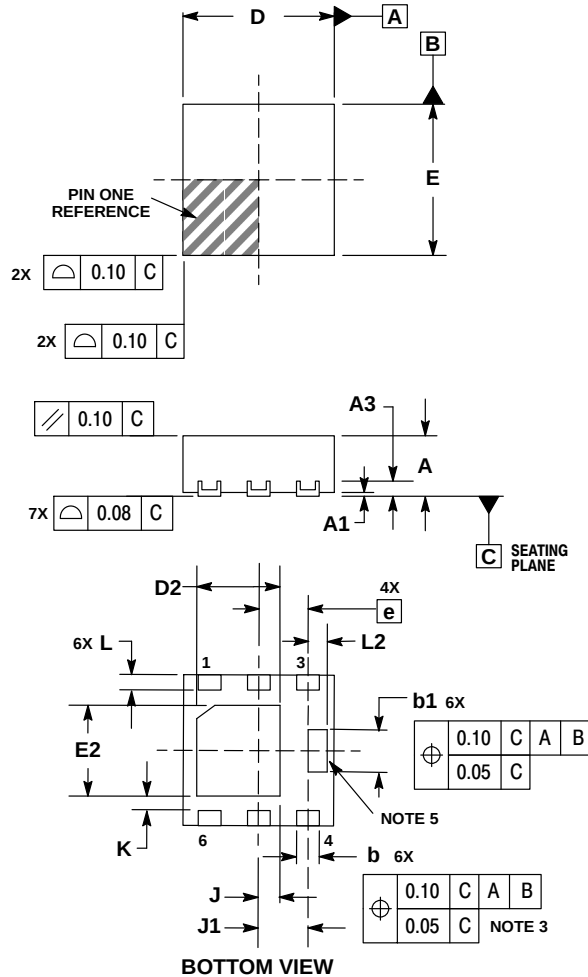
Figure 14. FET Thermal Response



WDFN6 2x2
CASE 506AP
ISSUE B

DATE 26 APR 2006

SCALE 4:1



STYLE 1:
PIN 1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN

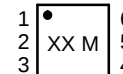
STYLE 2:
PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER
5. COLLECTOR
6. COLLECTOR

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
1. CENTER TERMINAL LEAD IS OPTIONAL. TERMINAL LEAD IS CONNECTED TO TERMINAL LEAD # 4.
2. PINS 1, 2, 5 AND 6 ARE TIED TO THE FLAG.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.25	0.35
b1	0.51	0.61
D	2.00 BSC	
D2	1.00	1.20
E	2.00 BSC	
E2	1.10	1.30
e	0.65 BSC	
K	0.15 REF	
L	0.20	0.30
L2	0.20	0.30
J	0.27 REF	
J1	0.65 REF	

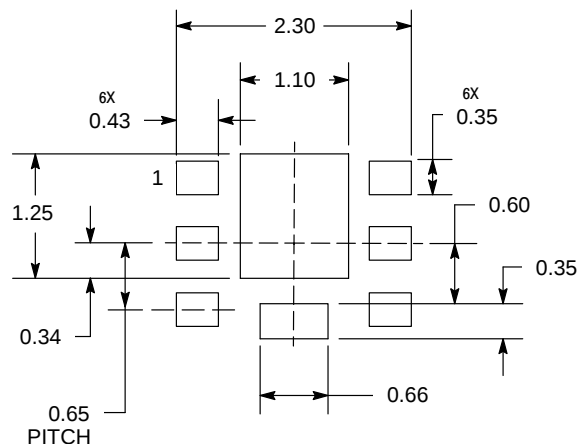
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERMASK DEFINED MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

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DESCRIPTION:	6 PIN WDFN 2X2, 0.65P	PAGE 1 OF 1

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